

FDJ129P

P-Channel -2.5 Vgs Specified PowerTrench® MOSFET

General Description

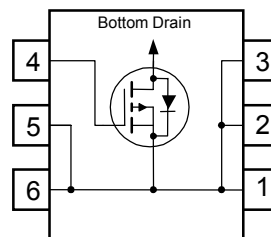
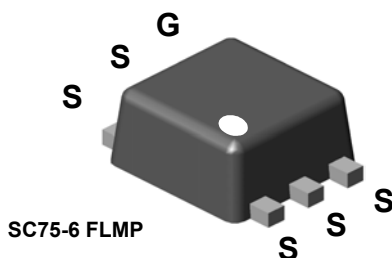
This P-Channel -2.5V specified MOSFET uses Fairchild's advanced low voltage PowerTrench process. It has been optimized for battery power management applications.

Applications

- Battery management
- Load switch

Features

- -4.2 A, -20 V. $R_{DS(ON)} = 70\text{ m}\Omega @ V_{GS} = -4.5\text{ V}$
 $R_{DS(ON)} = 120\text{ m}\Omega @ V_{GS} = -2.5\text{ V}$
- Low gate charge
- High performance trench technology for extremely low $R_{DS(ON)}$
- Compact industry standard SC75-6 surface mount package
- RoHS Compliant



Absolute Maximum Ratings T_A=25°C unless otherwise noted

Symbol	Parameter	Ratings	Units
V _{DSS}	Drain-Source Voltage	-20	V
V _{GSS}	Gate-Source Voltage	± 12	V
I _D	Drain Current – Continuous (Note 1a)	-4.2	A
	– Pulsed	-16	
P _D	Power Dissipation for Single Operation (Note 1a)	1.6	W
T _J , T _{STG}	Operating and Storage Junction Temperature Range	-55 to +150	°C

Thermal Characteristics

R _{θJA}	Thermal Resistance, Junction-to-Ambient (Note 1a)	77	°C/W
------------------	---	----	------

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
.A	FDJ129P	7"	8mm	3000 units

Electrical Characteristics

 $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
--------	-----------	-----------------	-----	-----	-----	-------

Off Characteristics

BV_{DSS}	Drain–Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = -250\ \mu\text{A}$	-20			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = -250\ \mu\text{A}$, Referenced to 25°C		-18		mV/ $^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -16\text{ V}, V_{GS} = 0\text{ V}$			-1	μA
I_{GSSF}	Gate–Body Leakage, Forward	$V_{GS} = 12\text{ V}, V_{DS} = 0\text{ V}$			100	nA
I_{GSSR}	Gate–Body Leakage, Reverse	$V_{GS} = -12\text{ V}, V_{DS} = 0\text{ V}$			-100	nA

On Characteristics (Note 2)

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = -250\ \mu\text{A}$	-0.6	-1.1	-1.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	$I_D = -250\ \mu\text{A}$, Referenced to 25°C		3		mV/ $^\circ\text{C}$
$R_{DS(on)}$	Static Drain–Source On–Resistance	$V_{GS} = -4.5\text{ V}, I_D = -4.2\text{ A}$ $V_{GS} = -2.5\text{ V}, I_D = -3.3\text{ A}$ $V_{GS} = -4.5\text{ V}, I_D = -4.2\text{ A}, T_J = 125^\circ\text{C}$		54 91 72	70 120 100	m Ω
$I_{D(on)}$	On–State Drain Current	$V_{GS} = -4.5\text{ V}, V_{DS} = -5\text{ V}$	-8			A
g_{FS}	Forward Transconductance	$V_{DS} = -5\text{ V}, I_D = -4.2\text{ A}$		11		S

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = -10\text{ V}, V_{GS} = 0\text{ V},$ $f = 1.0\text{ MHz}$		585	780	pF
C_{oss}	Output Capacitance			124	170	pF
C_{rss}	Reverse Transfer Capacitance			61	95	pF

Switching Characteristics (Note 2)

$t_{d(on)}$	Turn–On Delay Time	$V_{DD} = -10\text{ V}, I_D = -1\text{ A},$ $V_{GS} = -4.5\text{ V}, R_{GEN} = 6\ \Omega$		10	20	ns
t_r	Turn–On Rise Time			9	18	ns
$t_{d(off)}$	Turn–Off Delay Time			17	30	ns
t_f	Turn–Off Fall Time			10	20	ns
Q_g	Total Gate Charge		$V_{DS} = -10\text{ V}, I_D = -4.2\text{ A},$ $V_{GS} = -4.5\text{ V}$		4	6
Q_{gs}	Gate–Source Charge			1.1		nC
Q_{gd}	Gate–Drain Charge			1.2		nC

Drain–Source Diode Characteristics and Maximum Ratings

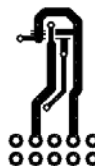
V_{SD}	Drain–Source Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_S = -1.5\text{ A}$ (Note 2)		-0.7	-1.2	V
t_{rr}	Diode Reverse Recovery Time	$I_F = -4.2\text{ A},$ $d_i/d_f = 100\text{ A}/\mu\text{s}$		16		nS
Q_{rr}	Diode Reverse Recovery Charge			13		nC

Notes:

- $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



- a) 77°C/W when mounted on a 1 in^2 pad of 2 oz copper.



- b) 110°C/W when mounted on a minimum pad of 2 oz copper.

Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width < 300 μs , Duty Cycle < 2.0%

Typical Characteristics

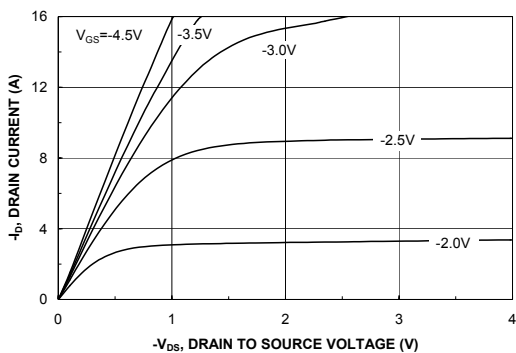


Figure 1. On-Region Characteristics.

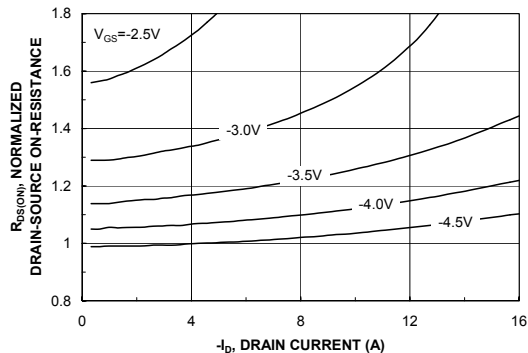


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

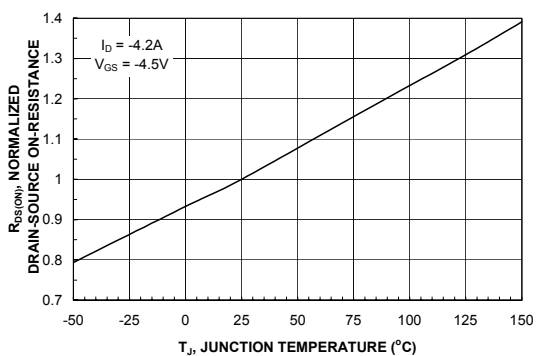


Figure 3. On-Resistance Variation with Temperature.

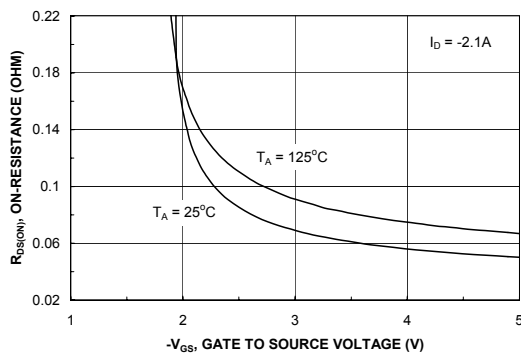


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

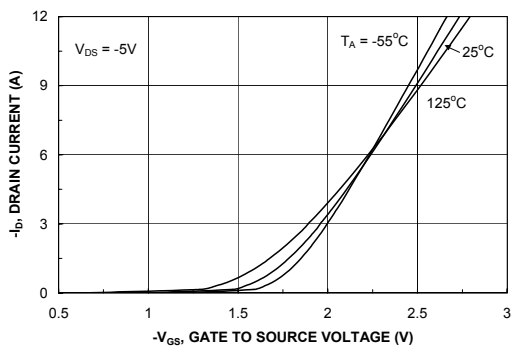


Figure 5. Transfer Characteristics.

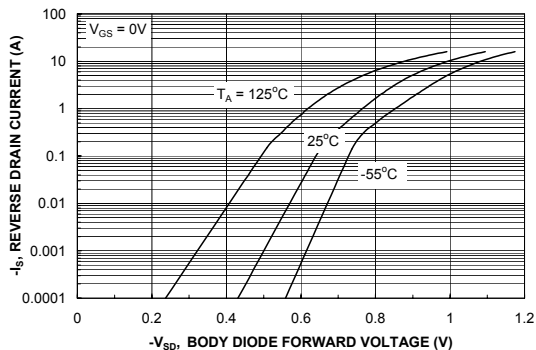


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics

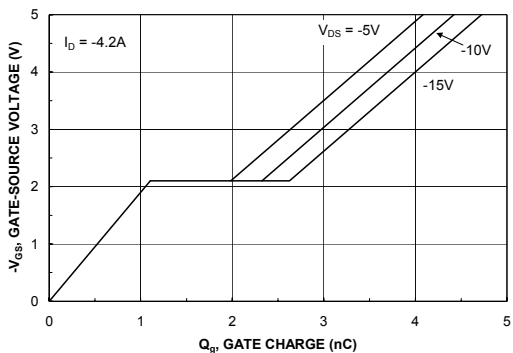


Figure 7. Gate Charge Characteristics.

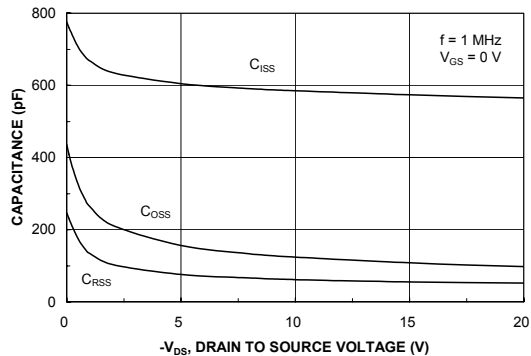


Figure 8. Capacitance Characteristics.

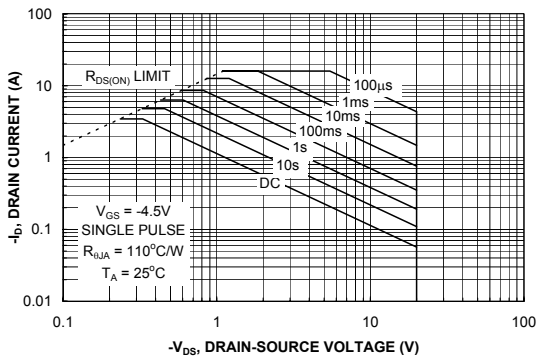


Figure 9. Maximum Safe Operating Area.

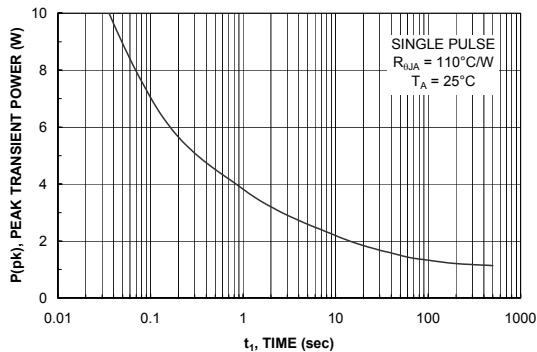


Figure 10. Single Pulse Maximum Power Dissipation.

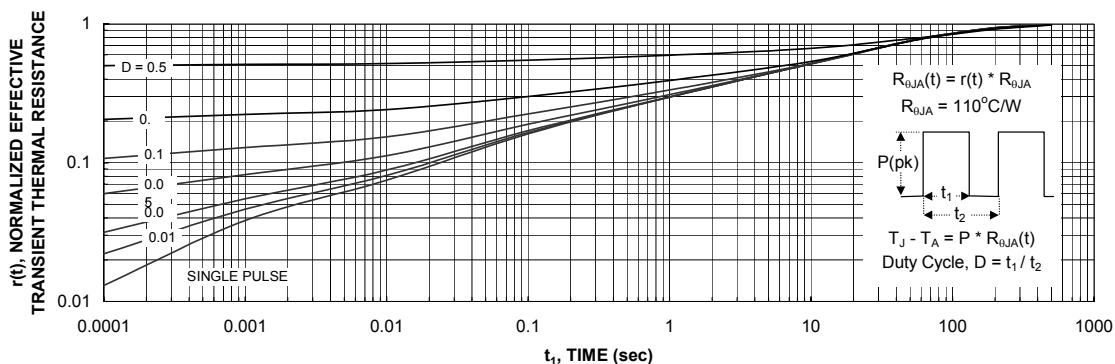
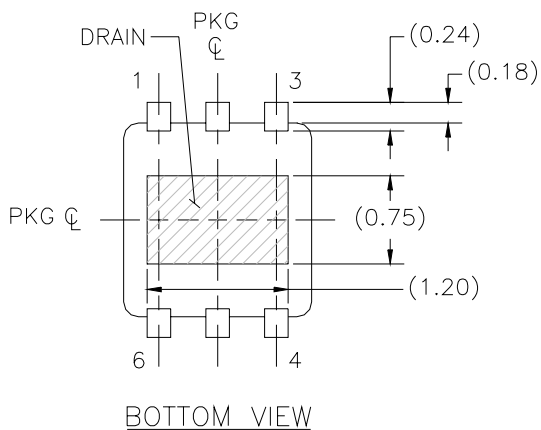
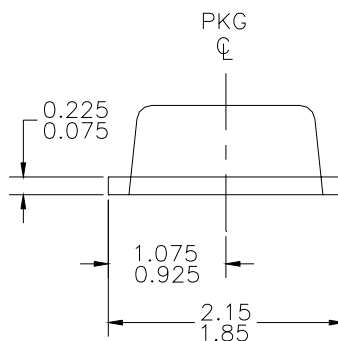
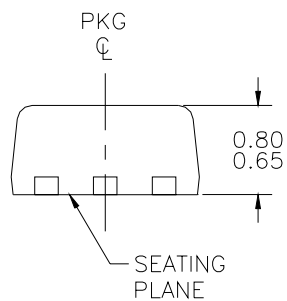
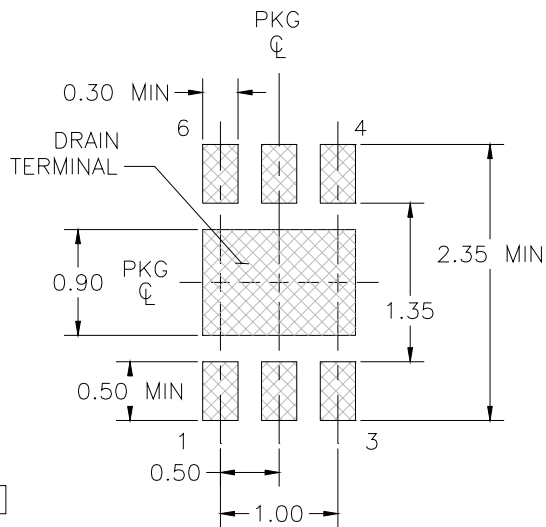
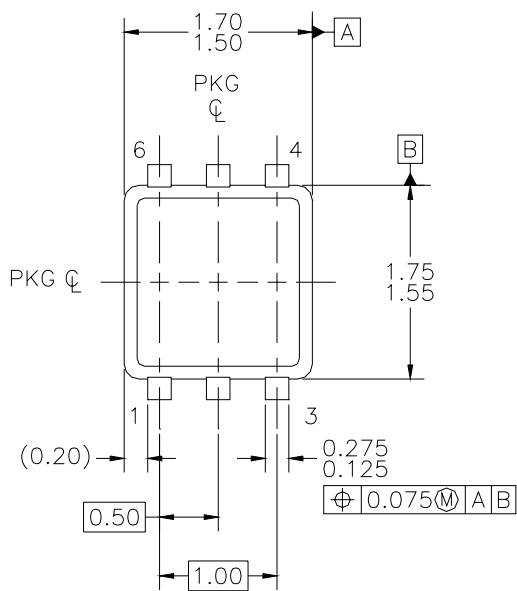


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1b. Transient thermal response will change depending on the circuit board design.

Dimensional Outline and Pad Layout




NOTES: UNLESS OTHERWISE SPECIFIED

- A) NO PACKAGE STANDARD REFERENCE AS OF JULY 13, 2000.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH.



TRADEMARKS

The following are registered and unregistered trademarks and service marks Fairchild Semiconductor owns or is authorized to use and is not intended to be an exhaustive list of all such trademarks.

- | | | | |
|-------------------------------------|--|----------------------------|----------------------|
| ACEx® | Green FPS™ | Power247® | SuperSOT™-8 |
| Build it Now™ | Green FPS™ e-Series™ | POWEREDGE® | SyncFET™ |
| CorePLUS™ | GTO™ | Power-SPM™ | The Power Franchise® |
| CROSSVOLT™ | i-Lo™ | PowerTrench® | the power franchise |
| CTL™ | IntelliMAX™ | Programmable Active Droop™ | TinyBoost™ |
| Current Transfer Logic™ | ISOPLANAR™ | QFET® | TinyBuck™ |
| EcoSPARK® | MegaBuck™ | QS™ | TinyLogic® |
| F Fairchild® | MICROCOUPLER™ | QT Optoelectronics™ | TINYOPTO™ |
| Fairchild Semiconductor® | MicroFET™ | Quiet Series™ | TinyPower™ |
| FACT Quiet Series™ | MicroPak™ | RapidConfigure™ | TinyPWM™ |
| FACT® | MillerDrive™ | SMART START™ | TinyWire™ |
| FAST® | Motion-SPM™ | SPM® | µSerDes™ |
| FastvCore™ | OPTOLOGIC® | STEALTH™ | UHC® |
| FPS™ | OPTOPLANAR® | SuperFET™ | UniFET™ |
| FRFET® |  PDP-SPM™ | SuperSOT™-3 | VCX™ |
| Global Power Resource SM | Power220® | SuperSOT™-6 | |

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

- Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
- A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild Semiconductor. The datasheet is printed for reference information only.